

Lonten N-channel 550V, 23A¹⁾, 0.14Ω LonFET™ Power MOSFET

Description

LonFET™ Power MOSFET is fabricated using **advanced super junction** technology. The resulting device has extremely low on resistance, making it especially suitable for applications which require superior power density and outstanding efficiency.

Features

- ◆ Ultra low $R_{DS(on)}$
- ◆ Ultra low gate charge (typ. $Q_g = 40nC$)
- ◆ 100% UIS tested
- ◆ RoHS compliant

Applications

- ◆ Power factor correction (PFC).
- ◆ Switched mode power supplies (SMPS).
- ◆ Uninterruptible power supply (UPS).

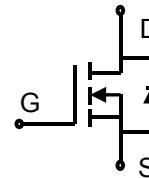
Product Summary

$V_{DS} @ T_{j,max}$	600V
$R_{DS(on),max}$	0.14Ω
I_{DM}	30A
$Q_{g,typ}$	40 nC

Pin Configuration



TO-220F



N-Channel MOSFET

Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	550	V
Continuous drain current ($T_c = 25^\circ C$)	I_D	10	A
($T_c = 100^\circ C$)		6.3	A
Pulsed drain current ²⁾	I_{DM}	30	A
Gate-Source voltage	V_{GSS}	± 30	V
Avalanche energy, single pulse ³⁾	E_{AS}	600	mJ
Power Dissipation	P_D	34	W
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	°C
Continuous diode forward current	I_S	10	A
Diode pulse current	$I_{S,pulse}$	30	A

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	3.7	°C/W
Thermal Resistance, Junction-to-Ambient ⁴⁾	$R_{\theta JA}$	60	°C/W

Package Marking and Ordering Information

Device	Device Package	Marking	Units/Tube
LSD55R140GF	TO-220F	LSD55R140GF	50

Electrical Characteristics
 $T_c = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static characteristics						
Drain-source breakdown voltage	BV_{DSS}	$V_{\text{GS}}=0 \text{ V}, I_{\text{D}}=0.25 \text{ mA}$	550	-	-	V
Gate threshold voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=0.25 \text{ mA}$	2.5	3.5	5.0	V
Drain cut-off current	I_{DSS}	$V_{\text{DS}}=550 \text{ V}, V_{\text{GS}}=0 \text{ V}, T_j = 25^\circ\text{C}$	-	-	5	μA
Gate leakage current, Forward	I_{GSSF}	$V_{\text{GS}}=30 \text{ V}, V_{\text{DS}}=0 \text{ V}$	-	-	100	nA
Gate leakage current, Reverse	I_{GSSR}	$V_{\text{GS}}=-30 \text{ V}, V_{\text{DS}}=0 \text{ V}$	-	-	-100	nA
Drain-source on-state resistance	$R_{\text{DS(on)}}$	$V_{\text{GS}}=10 \text{ V}, I_{\text{D}}=11.5 \text{ A}$	-			
		$T_j = 25^\circ\text{C}$	-	0.11	0.14	Ω
		$T_j = 150^\circ\text{C}$	-	0.26	-	
Gate resistance	R_{G}	$f=1 \text{ MHz}, \text{open drain}$	-	5.3	-	Ω
Dynamic characteristics						
Input capacitance	C_{iss}	$V_{\text{DS}} = 100 \text{ V}, V_{\text{GS}} = 0 \text{ V},$ $f = 250 \text{ kHz}$	-	1703	-	pF
Output capacitance	C_{oss}		-	78	-	
Reverse transfer capacitance	C_{rss}		-	2.8	-	
Turn-on delay time	$t_{\text{d(on)}}$	$V_{\text{DD}} = 400 \text{ V}, I_{\text{D}} = 11.5 \text{ A}$ $R_{\text{G}} = 5 \Omega, V_{\text{GS}} = 15 \text{ V}$	-	70	-	ns
Rise time	t_{r}		-	14	-	
Turn-off delay time	$t_{\text{d(off)}}$		-	72	-	
Fall time	t_{f}		-	7.7	-	
Gate charge characteristics						
Gate to source charge	Q_{gs}	$V_{\text{DD}} = 440 \text{ V}, I_{\text{D}} = 11.5 \text{ A},$ $V_{\text{GS}} = 0 \text{ to } 10 \text{ V}$	-	9	-	nC
Gate to drain charge	Q_{gd}		-	16.5	-	
Gate charge total	Q_{g}		-	40	-	
Gate plateau voltage	V_{plateau}		-	5.7	-	V
Reverse diode characteristics						
Diode forward voltage	V_{SD}	$V_{\text{GS}}=0 \text{ V}, I_{\text{F}}=23 \text{ A}$	-	-	1.1	V
Reverse recovery time	t_{rr}	$V_{\text{R}}=400 \text{ V}, I_{\text{F}}=11.5 \text{ A},$ $dI_{\text{F}}/dt=100 \text{ A}/\mu\text{s}$	-	166	-	ns
Reverse recovery charge	Q_{rr}		-	1.17	-	μC
Peak reverse recovery current	I_{rrm}		-	14.1	-	A

Notes:

1. The value reference TO-247 package.
2. Limited by maximum junction temperature, maximum duty cycle is 0.75.
3. $I_{\text{AS}} = 5 \text{ A}, L=48 \text{ mH}, V_{\text{DD}} = 60 \text{ V}, \text{Starting } T_j = 25^\circ\text{C}$.
4. The value of R_{thJA} is measured by placing the device in a still air box which is one cubic foot.

Electrical Characteristics Diagrams

Figure 1. Typ. Output Characteristics

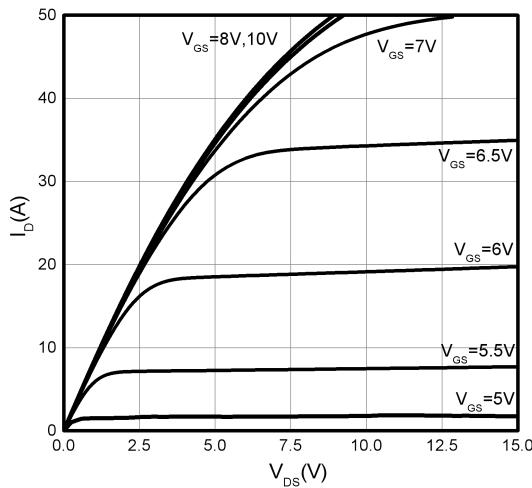


Figure 2. Transfer Characteristics

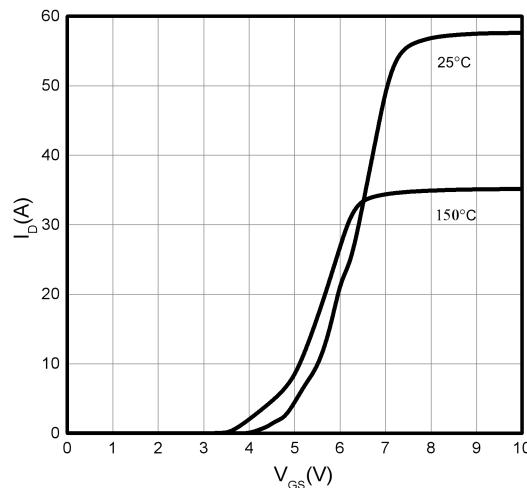


Figure 3. On-Resistance vs. Drain Current

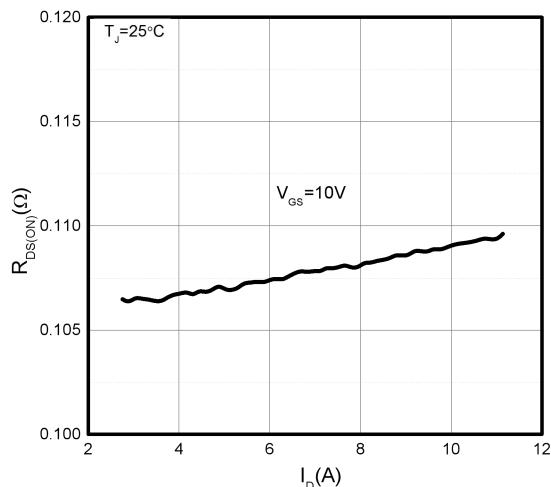


Figure 4. On-Resistance vs. Temperature

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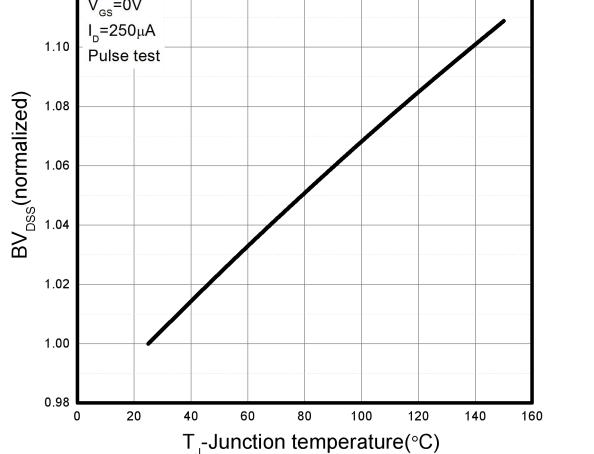
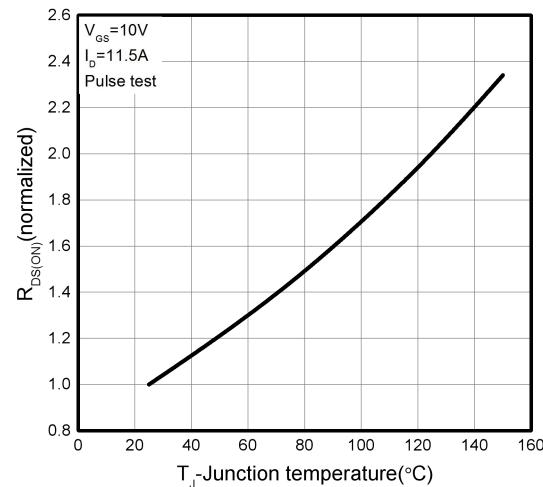


Figure 6. Threshold Voltage vs. Temperature

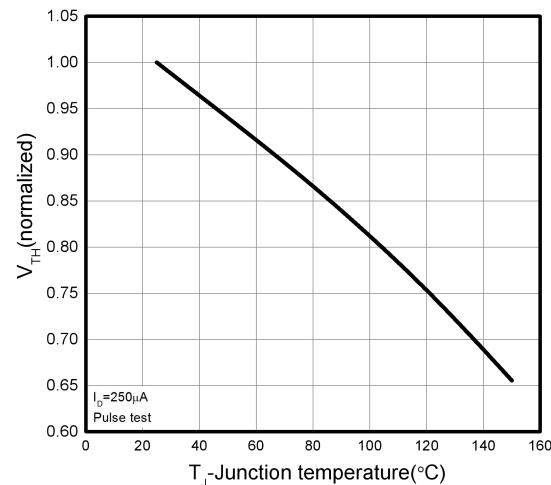


Figure 7.Body-Diode Characteristics

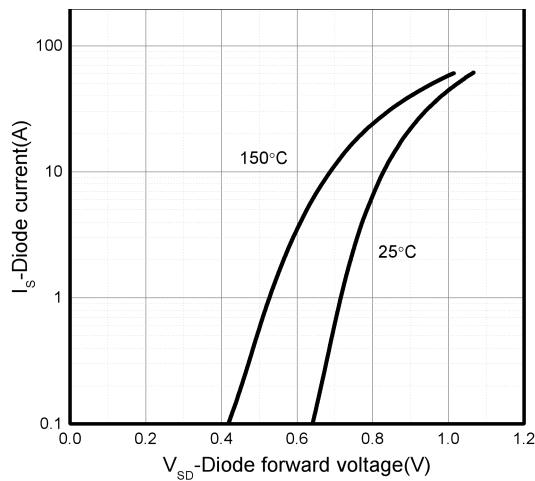


Figure 8.Capacitance Characteristics

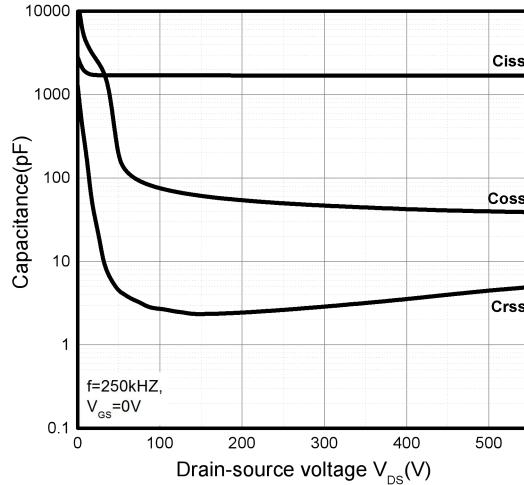


Figure 9.Gate Charge Characteristics

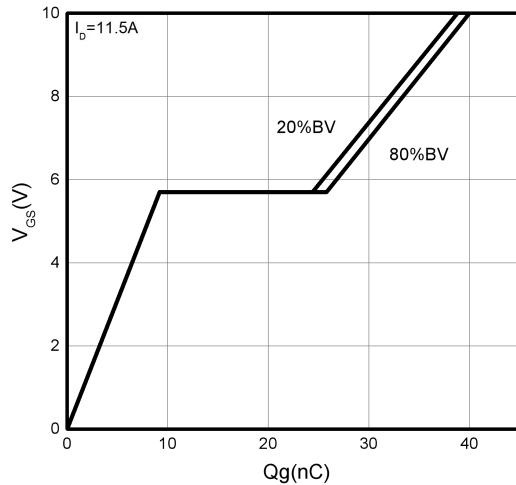


Figure 10.Drain Current Derating

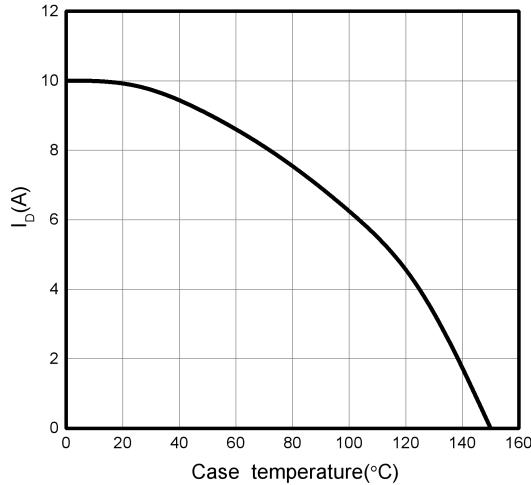


Figure 11.Power Dissipation vs.Temperature

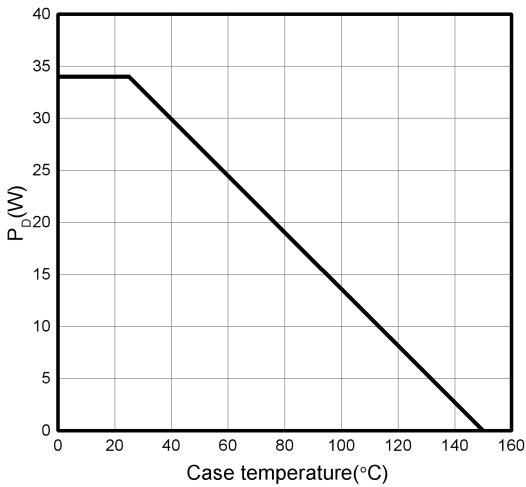


Figure 12: Safe Operating Area

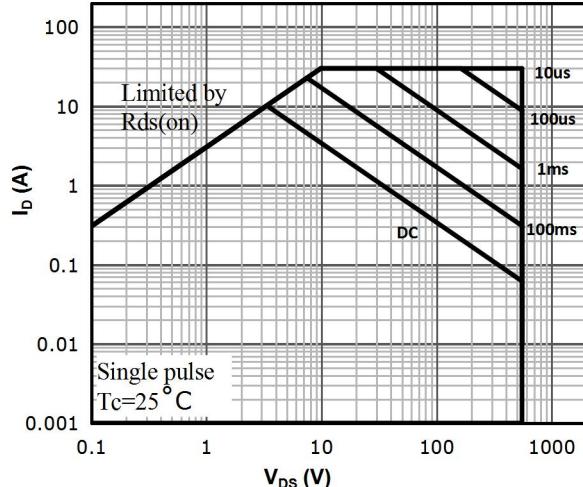
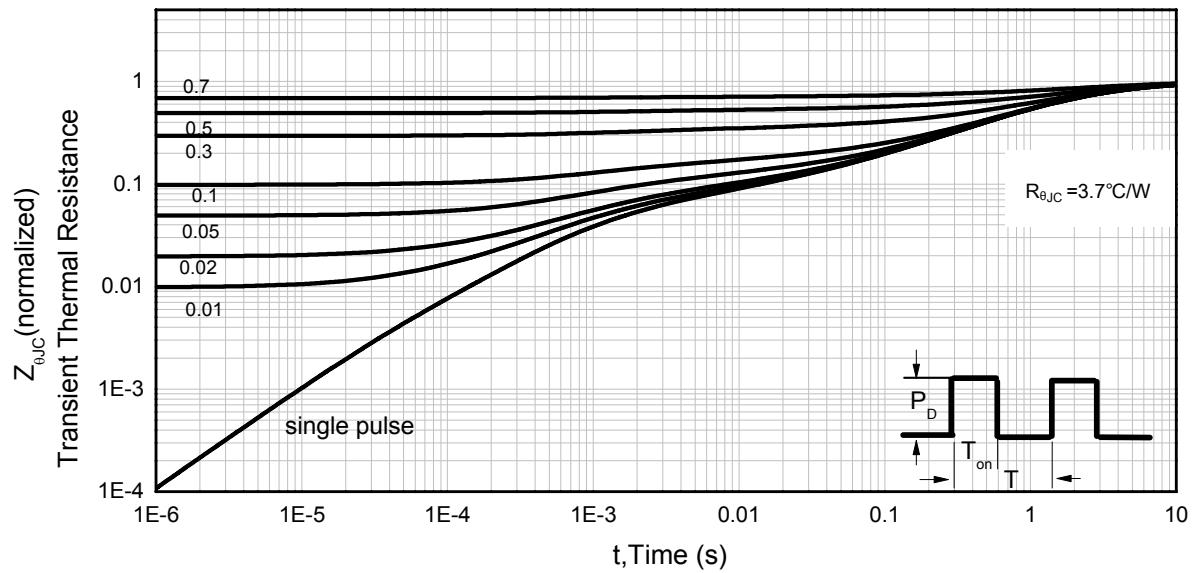
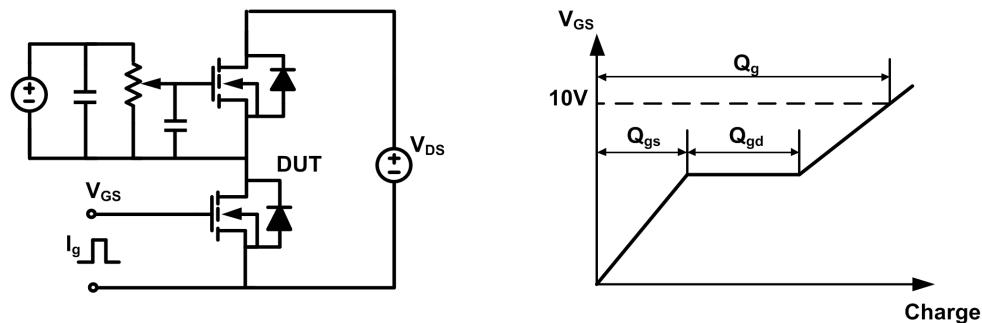


Figure 13. Normalized Maximum Transient Thermal Impedance (R_{θJC})

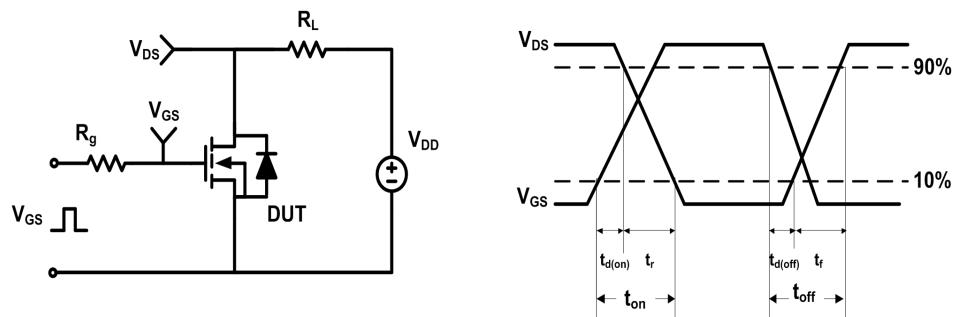


Test Circuit & Waveforms

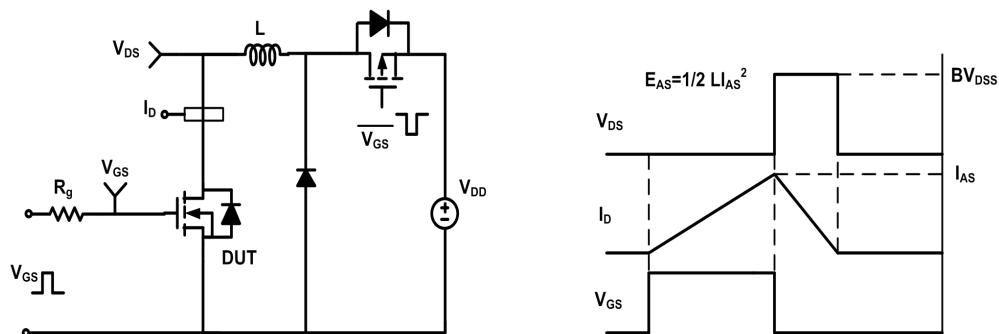
Gate Charge Test Circuit & Waveform



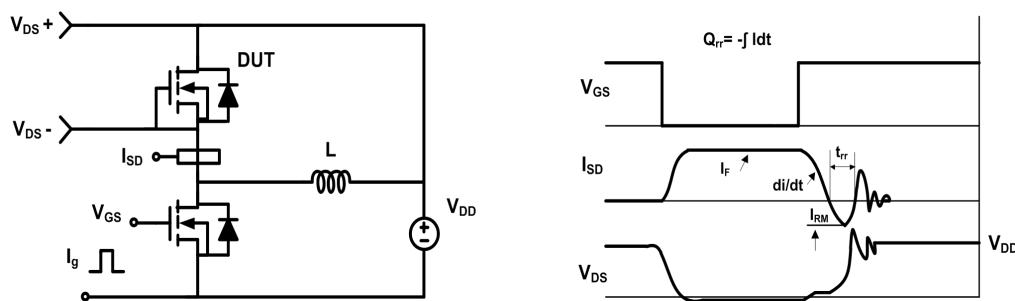
Resistive Switching Test Circuit & Waveform



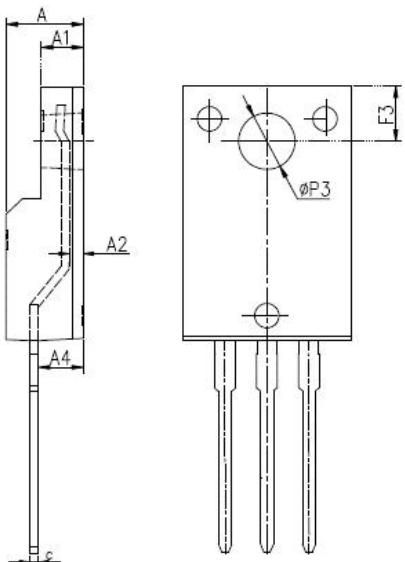
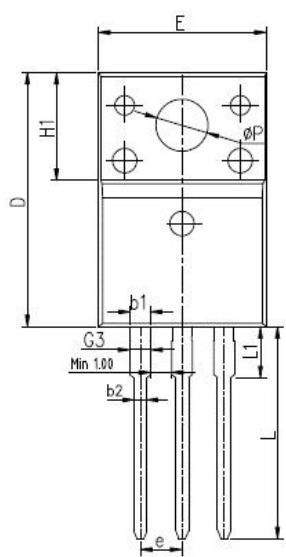
Unclamped Inductive Switching (UIS) Test Circuit & Waveform



Diode Recovery Test Circuit & Waveform



Mechanical Dimensions for TO-220F



DIMENSIONS IN MILLIMETERS		
SYMBOL	MIN	MAX
A	4.4	4.9
A1	2.34	2.74
A2	0.3	0.7
A4	2.5	2.96
c	0.4	0.7
D	15.57	16.4
E	9.96	10.4
H1	6.48	6.95
e	2.54BSC	
L	12.68	14.2
L1	2.88	3.6
ΦP	3	3.38
ΦP_3	3.15	3.65
F_3	3.15	3.45
G_3	1.15	1.58
b1	1.18	1.43
b2	0.7	1

Version Information

LSD55R140GF

Revision:2022-5-12,Rev 1.0

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